L Number	Hits	Search Text	DB	Time stamp
1	2	(underfill\$3 adhesives seal\$4) adj	USPAT;	2004/04/30 12:56
		(composition mixture\$1 paste slurry) same	US-PGPUB;	
		(solder metal\$4) near5 (particle\$1	EPO; JPO	
		filler\$1 powder\$1) same (curing hardening)		
		adj agent\$1		
2	2	((underfill\$3 adhesives seal\$4) adj	USPAT;	2004/04/30 12:55
		(composition mixture\$1 paste slurry) same	US-PGPUB;	
		(solder metal\$4) near5 (particle\$1	EPO; JPO	
		filler\$1 powder\$1) same (curing hardening)		
		adj agent\$1) and (underfill\$3 adhesives		
		seal\$4) same (curing hardening) adj		
		agent\$1		
3	17	,	USPAT;	2004/04/30 12:57
		(composition mixture\$1 paste slurry) same	US-PGPUB;	
		(solder metal\$4) near5 (particle\$1	EPO; JPO	
	17	filler\$1 powder\$1) same (curing hardening)	IIODAM.	2004/04/20 12:57
4	17		USPAT; US-PGPUB;	2004/04/30 12:57
		(composition mixture\$1 paste slurry) same	EPO; JPO	
		(solder metal\$4) near5 (particle\$1 filler\$1 powder\$1) same (curing	EPO; JPO	
		hardening)) and (underfill\$3 adhesives		
		seal\$4) same (curing hardening)		
_	57	underfill\$3 adj (composition mixture\$1	USPAT;	2004/04/27 16:44
	3,	paste slurry)	US-PGPUB;	2004/04/27 10:44
		paste starry,	EPO; JPO	
_	6	(("6356333") or ("20020127406") or	USPAT;	2004/04/26 12:34
		("5128746") or ("6063647") or ("6168972")	US-PGPUB;	
		or ("6260264")).PN.	EPO; JPO	
_	17		USPAT;	2004/04/27 16:47
		mixture\$1 paste slurry) same (solder	US-PGPUB;	
		metal\$4) near5 (particle\$1 grain\$1 ball\$1	EPO; JPO	
		filler\$1 powder\$1)		
-	17	((underfill\$3 adhesives) adj (composition	USPAT;	2004/04/30 12:51
		mixture\$1 paste slurry) same (solder	US-PGPUB;	
		metal\$4) near5 (particle\$1 grain\$1 ball\$1	EPO; JPO	
		filler\$1 powder\$1)) and (underfill\$3		
		adhesives) same (solder metal\$4)		1